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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: **Koji NOZAKI, et al**

Group Art Unit: **1752**

Serial No.: **10/623,679**

Examiner: **WALKE, AMANDA C**

Filed: **July 22, 2003**

P.T.O. Confirmation No.: **5083**

For: **RESIST PATTERN THICKENING MATERIAL, RESIST PATTERN AND
RPROCESS FOR FORMING THE SAME, AND SEMICONDUCTOR DEVICE
AND PROCESS FOR MANUFACTURING THE SAME**

Attorney Docket No.: **030891**

Customer Number: **38834**

AMENDMENT UNDER 37 CFR §1.111

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

November 3, 2004

Sir:

In response to the Office Action dated August 3, 2004, please amend the above-identified application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks begin on page 10 of this paper.